

## Using UV Lasers for Kapton Cutting

During cover layer cutting, holes are cut through the Kapton PI film before it's laminated on a circuit board. The process demands accuracy and control, especially as the final result is often used on tiny boards without much tolerance for imperfections.

The LPKF UV lasers we work with are ideal for this intricate process. Laser ablation gives us the control we need to create detailed cut-outs.

For example, we might use an LPKF laser to cut squares out of PI film to expose copper pads so that they can have components soldered to them later. (In such a case, the PI film is acting as a solder mask to prevent the solder joints from shorting between the copper pads.)

UV lasers make fine cuts with high accuracy. Because they avoid problems caused by chemical, heat, and mechanical methods, they allow us to complete the project to your exact specifications.

## Our Other Laser-Cutting Services

We offer a wide range of [laser-cutting services](#), including [laser skiving](#), [laser depaneling](#), [laser ablation routing](#), and more. We work with both [UV lasers](#) and [infrared lasers](#) to give you the choice of the best method for your project.

## Find Out How We Can Help

Our technical engineers walk you every step of the way through the manufacturing process. We'd be happy to talk more about your project and how we can help.

[Laser Cut Kapton - A-Laser Precision Laser Cutting](#)

[A-Laser Precision Laser Cutting - Laser Ablation, UV and IR Lasers](#)